

## PATENT ASSIGNMENT COVER SHEET

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<b>Name</b>	<b>Execution Date</b>
HONG KONG BAPTIST UNIVERSITY	06/05/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HKBU R&D LICENSING LIMITED
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<b>State/Country:</b>	HONG KONG
<b>PROPERTY NUMBERS Total: 1</b>	
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<b>Patent Number:</b>	9932663
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<b>NAME OF SUBMITTER:</b>	SAM YIP
<b>SIGNATURE:</b>	/SAM YIP/
<b>DATE SIGNED:</b>	06/19/2020
<b>Total Attachments: 2</b>	
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## Assignment

THIS ASSIGNMENT, made by Hong Kong Baptist University (hereinafter referred to as Assignor), an educational institutional of Hong Kong having its principal place of business at Kowloon Tong, Kowloon, Hong Kong.

WHEREAS, Assignor is the owner in the patent application entitled SAPPHIRE THIN FILM COATED SUBSTRATE set forth in a Patent application for Letters Patent of the United States, filed with the United States Patent and Trademark Office as Non-Provisional Application Serial No. 15/597,170 on 17 May 2017 and issued on 3 April 2018 under patent number 9,932,663.

WHEREAS, HKBU R&D Licensing Limited, a Limited Liability Company organized under and pursuant to the laws of Hong Kong having its principal place of business at DLB825, 8/F, David C. Lam Building, Shaw Campus, Hong Kong Baptist University, Kowloon Tong, Kowloon, Hong Kong, (hereinafter referred to as Assignees), is desirous of acquiring the entire right, title and interest in and to said inventions and said Non-Provisional Application for Letters Patent of the United States, and in and to any Letters Patent of the United States to be obtained therefore and thereon.

NOW, THEREFORE, for good and sufficient consideration, the receipt of which is hereby acknowledged, Assignor have sold, assigned, transferred and set over, and by these presents do sell, assign, transfer and set over, unto Assignees, their successors, legal representatives and assigns, the entire right, title and interest in and to the above-mentioned inventions and application for Letters Patent, and in and to any and all direct and indirect divisions, continuations and continuations-in-part of said application, and any and all Letters Patent in the United States and all foreign countries which may be granted therefore and thereon, and reissues, reexaminations and extensions of said Letters Patent, and all rights under the International Convention for the Protection of Industrial Property, the same to be held and enjoyed by Assignees, for their own use and benefit and the use and benefit of their successors, legal representatives and assigns, to the full end of the term or terms for which Letters Patent may be granted and/or extended, as fully and entirely as the same would have been held and enjoyed by Assignor, had this sale and assignment not been made.

AND for the same consideration, Assignor hereby represent and warrant to Assignees, their successors, legal representatives and assigns, that, at the time of execution and delivery of these presents, except for any rights, titles and/or interests that have arisen to Assignees under law or that have already been transferred to Assignees, Assignor are the sole and lawful owners of the entire right, title and interest in and to the said inventions and application for Letters Patent above-mentioned, and that the same are unencumbered and that Assignor have good and full right and lawful authority to sell and convey the same in the manner herein set forth.

AND for the same consideration, Assignor hereby covenant and agree to and with Assignees, their successors, legal representatives and assigns, that Assignor will sign all papers and documents, take all lawful oaths and do all acts necessary or required to be done for the procurement, maintenance, enforcement and defense of any Letters Patent and applications for Letters Patent for said inventions, whenever counsel of Assignees, or counsel of their successors, legal representatives and assigns, shall advise; that any proceeding in connection with said inventions, or said Patent application for Letters Patent, or any proceeding in connection with any Letters Patent or applications for Letters Patent for said inventions in any country, including but not limited to interference proceedings, is lawful and desirable; or, that any division, continuation or continuation-in-part of any application for Letters Patent, or any reissue, reexamination or extension of any Letters Patent, to be obtained thereon, is lawful and desirable.

AND Assignor hereby request the Commissioner of Patent and Trademarks to issue said Letters Patent of the United States to Assignees, as Assignees of said inventions and the Letters Patent to be issued thereon, for the sole use and benefit of Assignees, their successors, legal representatives and assigns.

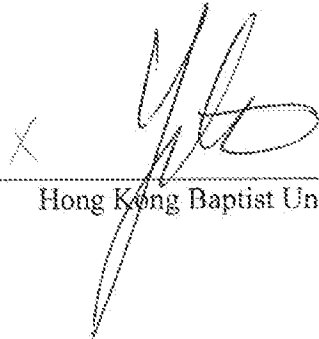
AND Assignor hereby grant the following the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document:

Idea Intellectual Limited

and all practitioners at Customer Number: 140382

AND Assignor acknowledge an obligation of assignment of this invention to Assignees at the time the invention was made.

Date: 5 June 2020

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Hong Kong Baptist University